



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: RAEDER Examiner: Nguyen, D.
Serial No.: 09/383,876 Group Art Unit: 3723
Filed: August 26, 1999 Docket No.: AMDA.316PA
Title: POLISHING UNIFORMITY VIA PAD CONDITIONING

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this communication is being deposited in the United States Postal Service, as first class mail, in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231, on July 14, 2000.

By

Lynda J. BaberOFFICE ACTION RESPONSE

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

In response to the Office Action dated June 14, 2000, please amend the above-identified patent application as follows:

In The Claims

Please add new claim 17 and amend claim 1 as follows:

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1. (Amended) A method for chemical-mechanical polishing a wafer using a CMP apparatus having a polishing table including a polishing pad and a wafer carrier adapted to carry a wafer relative to the center of the polishing table, the method comprising:
using the polishing pad [and] , polishing the wafer at a position relative to the center;
determining that the wafer is being polished in a center-offset manner; and
conditioning the pad as a function of the wafer being polished in the center-offset manner.

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